

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"6143432".pn.	USPAT; EPO; JPO	OR	ON	2005/06/06 12:10
L15	3809	ceramic with (metal\$4 conductive) and (covalent chemical\$2 ionic) near2 bond\$3 and (board substrate)	USPAT; EPO; JPO	OR	ON	2005/06/06 12:11
L16	309	ceramic with (metal\$4 conductive) and (covalent chemical\$2 ionic) near2 bond\$3 with temperature and (board substrate)	USPAT; EPO; JPO	OR	ON	2005/06/06 12:25
L17	11	ceramic with (metal\$4 conductive) with bond\$3 and covalent near2 bond\$3 with temperature and (board substrate)	USPAT; EPO; JPO	OR	ON	2005/06/06 12:28
L18	26	ceramic near3 (metal\$4 conductive) and covalent near2 bond\$3 with temperature and (board substrate)	USPAT; EPO; JPO	OR	ON	2005/06/06 15:28
L19	1148	ceramic near3 (metal\$4 conductive) and thermal\$3 near3 (plate core net\$1work) and (board substrate)	USPAT; EPO; JPO	OR	ON	2005/06/06 15:29
L20	431	ceramic near3 (metal\$4 conductive) and thermal\$3 near3 (plate core net\$1work) and (board substrate) and @pd<"19980101"	USPAT; EPO; JPO	OR	ON	2005/06/06 15:30
L21	203	ceramic near3 (metal\$4 conductive) and thermal\$3 near3 (plate core net\$1work) and (board substrate) same (ic chip semiconductor) and @pd<"19980101"	USPAT; EPO; JPO	OR	ON	2005/06/06 15:30
S57	13	"29"/\$ and S56	USPAT; EPO; JPO	OR	ON	2005/05/25 10:51
S58	30	(ceramic aluminate silicate) same covalent near2 bond\$3 same (conduct\$3 metal\$3 cu copper al aluminum) same temperature and @pd<"19970101"	USPAT; EPO; JPO	OR	ON	2005/06/02 16:57
S59	56	(ceramic aluminate silicate) same covalent near2 bond\$3 same (conduct\$3 metal\$3 copper aluminum) and temperature and @pd<"19970101" and (board substrate)	USPAT; EPO; JPO	OR	ON	2005/05/25 11:03

S60	2	(ceramic aluminate silicate) same covalent near2 bond\$3 same (conduct\$3 metal\$3 cu copper al aluminum) same temperature and electrical near2 (conduct3 wire trace line network) and thermal near2 (conduct3 wire trace line network)	USPAT; EPO; JPO	OR	ON	2005/06/02 17:15
S61	2	(ceramic aluminate silicate) same covalent near2 bond\$3 same (conduct\$3 metal\$3 cu copper al aluminum) and electrical near2 (conduct3 wire trace line network) and thermal near2 (conduct3 wire trace line network)	USPAT; EPO; JPO	OR	ON	2005/06/02 17:15
S62	159	(ceramic aluminate silicate) same (conduct\$3 metal\$3 cu copper al aluminum) and electrical near2 (conduct3 wire trace line network) and thermal near2 (conduct3 wire trace line network)	USPAT; EPO; JPO	OR	ON	2005/06/02 17:26
S63	126	(ceramic aluminate silicate) same (conduct\$3 metal\$3 cu copper al aluminum) and electrical near2 (conduct3 wire trace line network) and thermal near2 (conduct3 core plate network)	USPAT; EPO; JPO	OR	ON	2005/06/02 17:26
S64	0	thermal near2 (plane network) and circuit adj1 board with (ceramic aln aluninate silicate) and (ion convalent) near2 bond\$3	USPAT; EPO; JPO	OR	ON	2005/06/03 15:21
S65	0	thermal near2 (plane network) same circuit adj1 board with (ceramic aln aluninate silicate) same bond\$3	USPAT; EPO; JPO	OR	ON	2005/06/03 15:22
S66	3	thermal near2 (plane network) same circuit adj1 board same (ceramic aln aluninate silicate) same bond\$3	USPAT; EPO; JPO	OR	ON	2005/06/03 15:22
S67	15	thermal near2 (plane core network) same circuit adj1 board with (ceramic aln aluninate silicate)	USPAT; EPO; JPO	OR	ON	2005/06/03 15:24
S68	28	"361"/\$ and thermal near2 (plane core network) and circuit adj1 board with (ceramic aln aluninate silicate)	USPAT; EPO; JPO	OR	ON	2005/06/03 15:26
S69	26	"174"/\$ and thermal near2 (plane core network) and circuit adj1 board with (ceramic aln aluninate silicate)	USPAT; EPO; JPO	OR	ON	2005/06/03 15:27

S70	12	"29"/\$ and thermal near2 (plane core network) and circuit adj1 board with (ceramic aln aluninate silicate)	USPAT; EPO; JPO	OR	ON	2005/06/03 15:27
S71	36	("2269523" "3091028" "3110571" "3226822" "3558755" "3668758" "3736649" "3994430" "4505418" "4525841" "4624404" "4669535" "4731701" "4811166" "5020586" "5036584" "5040292" "5082163" "5097385" "5125451" "5126511" "5168348" "5176309" "5269372" "5303555" "5304846" "5370178" "5380956" "5381859" "5386339" "5394299").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 16:17
S72	1	"4129243".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/03 17:18
S73	1191	(chemical ion direct covalent) near2 bond\$3 same (ceramic aln aluninate silicate) same (metal\$4 conduct\$3)	USPAT; EPO; JPO	OR	ON	2005/06/03 17:19
S74	1175	(chemical ion direct covalent) near2 bond\$3 same (ceramic aluninate silicate) same (metal\$4 conduct\$3)	USPAT; EPO; JPO	OR	ON	2005/06/03 17:20
S75	223	(chemical ion direct covalent) near2 bond\$3 same (ceramic aluninate silicate) same (metal\$4 conduct\$3) and circuit near2 (board substrate)	USPAT; EPO; JPO	OR	ON	2005/06/03 17:23
S76	58	(chemical ion covalent) near2 bond\$3 same (ceramic aluninate silicate) same (metal\$4 conduct\$3) and circuit near2 (board substrate)	USPAT; EPO; JPO	OR	ON	2005/06/03 17:54
S77	116	(ceramic aluninate silicate) same (metal\$4 conduct\$3) and circuit near2 (board substrate) same capacitor near2 (embed\$4 within)	USPAT; EPO; JPO	OR	ON	2005/06/03 17:58
S78	2	(ceramic aluninate silicate) same circuit near2 (board substrate) same capacitor near2 (embed\$4 within) and thermal\$3 near2 (network core plane)	USPAT; EPO; JPO	OR	ON	2005/06/03 17:59
S79	13	(ceramic aluninate silicate) same circuit near2 (board substrate) and capacitor near2 (embed\$4 within) and thermal\$3 near2 (network core plane plate)	USPAT; EPO; JPO	OR	ON	2005/06/03 18:00

S80	21	(ceramic aluninate silicate) with (board substrate) and capacitor near2 (embed\$4 within) and thermal\$3 near2 (network core plane plate)	USPAT; EPO; JPO	OR	ON	2005/06/03 18:02
S81	33	(ceramic aluninate silicate) same (board substrate) and capacitor near3 (embed\$4 within) and thermal\$3 near2 (network core plane plate)	USPAT; EPO; JPO	OR	ON	2005/06/03 18:03